

Press release

06/12/2013

EmPower-Consortium launches innovative project for optimised use of energy

Optimised use of generated energy and specifically the increasing “electrification” of daily life poses significant challenges to the current methods and concepts for delivering power to point-of-use.

EmPower brings together leaders from the Automotive, Semiconductor, Process & Equipment and Packaging segments to focus on new and efficient methods to deliver energy to point of use.

Targets include the improvement of processes for semiconductor manufacturing, development of new concepts for component packaging, and design of products for optimum management of energy.

The consortium consists of the following members:

- AT&S – leader in the field of embedded component packaging
- Continental – leading Tier #1 automotive supply chain partner
- STMicro – leader in Power Semiconductor design and manufacturing
- TU Wien – world-class thermal simulation and modelling
- TU Berlin – world-class University with capability in the field of power semiconductors
- Atotech – leading process and equipment solutions provider to the Electronics industry
- Ilfa – European PCB manufacturer focussed on high technology, high mix production
- Fundico – focus on the project management deliverables

Hannes Stahr of AT&S, the project coordinator “EmPower is the spearhead for the development of new power packaging concepts, and will deliver new products in to the field of high efficiency, high power delivery packages. By working with European leaders in this field we are confident to establish standards for new products that will be globally rolled out, and establish European methods as the standard for this new exciting segment.”

Mark Beesley, Chief Operating Officer of Advanced Packaging at AT&S “Our targets include the development, industrialisation and ramp up of brand new products and concepts to deliver next generation performance benchmarks for power delivery. EmPower will establish the framework of competence and capability to enable that to happen here, in Europe.”

EmPower is the follower project of the highly successful HERMES Framework 7 funded European Union project, and brings European Research, Development and Industrialisation capability to the field of next generation power semiconductor packaging. EmPower is part of the “Mobilität der Zukunft” program (Mobility of the Future). EmPower has a total project volume in excess of five million Euros and a significant funded project in the Catrene framework.

About AT&S

AT & S Austria Technologie & Systemtechnik Aktiengesellschaft (AT&S) is European market leader and one of the world's leading producers of high-end printed circuit boards. AT&S is especially well positioned worldwide in the highest tech market segment for HDI microvia printed circuit boards, which are chiefly used in mobile devices. The Group is also highly successful in the automotive printed circuit board market, and in the industrial and medical technology sectors. In 2013 AT&S took the latest step in implementing its high-tech strategy by entering the IC substrate business as part of a joint venture with a leading global semiconductor manufacturer. As an international growth enterprise AT&S has a global presence, with three production facilities in Austria (Leoben, Fehring) and one each in India (Nanjangud), China (Shanghai, Chongqing) and Korea (Ansan, near Seoul). It currently employs some 7,100 people.

For more information visit www.ats.net.

Press contact

Christina Schuller, Head of Corporate Communications
AT & S Austria Technologie & Systemtechnik AG
+43 3842 200-5908, c.schuller@ats.net, www.ats.net